IRFE110 (JANTX2N6782U)

PD-91699C

Repetitive Avalanche and dv/dt Rated Power MOSFET
Surface Mount (LCC-18)
100V, 3.5A, N-channel

Features

- Surface mount
- Small footprint
- Alternative to TO-39 Package
- Hermetically sealed
- Dynamic dv/dt rating
- Avalanche energy rating
- Simple drive requirements
- Light weight
- ESD rating: Class 1A per MIL-STD-750, Method 1020

Product Summary

- **BV_{DSS}:** 100V
- **I_D:** 3.5A
- **$R_{DS(on),max}$:** 0.6Ω
- **$Q_{G,max}$:** 8.1nC
- **REF:** MIL-PRF-19500/556

LCC-18

Potential Applications

- DC-DC converter
- Motor drives

Product Validation

Qualified according to MIL-PRF-19500 for space applications

Description

The leadless chip carrier (LCC) package represents the logical next step in the continual evolution of surface mount technology. Desinged to be a close replacement for the TO-39 package, the LCC will give designers the extra flexibility they need to increase circuit board density. IR HiRel has engineered the LCC package to meet the specific needs of the power market by increasing the size of the bottom source pad, thereby enhancing the thermal and electrical performance. The lid of the package is grounded to the source to reduce RF interference.

Ordering Information

Table 1 Ordering options

Part number	Package	Screening Level
IRFE110	LCC-18	COTS
JANTX2N6782U	LCC-18	JANTX
JANTXV2N6782U	LCC-18	JANTXV

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1 Absolute Maximum Ratings

Table 2 Absolute Maximum Ratings

Symbol	Parameter	Value	Unit
I_{D1} @ V_{GS} = 10V, T_C = 25°C	Continuous Drain Current	3.5	A
I_{D2} @ V_{GS} = 10V, T_C = 100°C	Continuous Drain Current	2.25	A
I_{DM} @ T_C = 25°C	Pulsed Drain Current [1]	14	A
P_D @ T_C = 25°C	Maximum Power Dissipation	15	W
	Linear Derating Factor	0.12	W/°C
V_{GS}	Gate-to-Source Voltage	± 20	V
E_{AS}	Single Pulse Avalanche Energy [2]	7.0	mJ
I_{AR}	Avalanche Current [1]	3.5	A
E_{AR}	Repetitive Avalanche Energy [1]	1.5	mJ
dv/dt	Peak Diode Reverse Recovery [3]	9.0	V/ns
T_J T_{STG}	Operating Junction and Storage Temperature Range	-55 to +150	°C
	Lead Temperature	300 (for 5s)	
	Weight	0.42 (Typical)	g

[1] Repetitive Rating; Pulse width limited by maximum junction temperature.

[2] V_{DD} = 25V, starting T_J = 25°C, L = 1.15mH, Peak I_L = 3.5A

[3] $I_{SD} \leq$ 3.5A, di/dt ≤ 75A/µs, $V_{DD} \leq$ 100 V, $T_J \leq$ 150°C

2 Device Characteristics

2.1 Electrical Characteristics

Table 3 Static and Dynamic Electrical Characteristics @ T_j = 25°C (Unless Otherwise Specified)

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions
BV_{DSS}	Drain-to-Source Breakdown Voltage	100	—	—	V	V_{GS} = 0V, I_D =1.0mA
$\Delta BV_{DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	—	0.12	—	V/°C	Reference to 25°C, I_D = 1.0mA
$R_{DS(on)}$	Static Drain-to-Source On-State Resistance	—	—	0.60	Ω	V_{GS} =10 V, I_{D2} = 2.25A [1]
		—	—	0.61		V_{GS} = 10V, I_{D2} = 3.5A [1]
$V_{GS(th)}$	Gate Threshold Voltage	2.0	—	4.0	V	V_{DS} = V_{GS}, I_D = 250µA
Gfs	Forward Transconductance	0.8	—	—	S	V_{DS} = 15V, I_{D2} = 2.25A [1]
I_{DSS}	Zero Gate Voltage Drain Current	—	—	25	µA	V_{DS} = 80V, V_{GS} = 0V
		—	—	250		V_{DS} = 80V, V_{GS} = 0V, T_J = 125°C
I_{GSS}	Gate-to-Source Leakage Forward	—	—	100	nA	V_{GS} = 20V
	Gate-to-Source Leakage Reverse	—	—	-100		V_{GS} = -20V
Q_G	Total Gate Charge		—	8.1	nC	I_{D1} = 3.5A V_{DS} = 50V V_{GS} = 10V
Q_{GS}	Gate-to-Source Charge		—	1.7		
Q_{GD}	Gate-to-Drain (‘Miller’) Charge		—	4.5		
$t_{d(on)}$	Turn-On Delay Time	—	—	15	ns	I_{D1} = 3.5A ** V_{DD} = 50V R_G = 7.5Ω V_{GS} = 10V
t_r	Rise Time	—	—	25		
$t_{d(off)}$	Turn-Off Delay Time	—	—	25		
t_f	Fall Time	—	—	20		
L_s +L_D	Total Inductance	—	6.1	—	nH	Measured from the center of drain pad to center of source pad
C_{iss}	Input Capacitance	—	190	—	pF	V_{GS} = 0V V_{DS} = 25V f = 1.0MHz
C_{oss}	Output Capacitance	—	86	—		
C_{rss}	Reverse Transfer Capacitance	—	13	—		

** Switching speed maximum limits are based on manufacturing test equipment and capability.

[1] Pulse width ≤ 300 µs; Duty Cycle ≤ 2%

2.2 Source-Drain Diode Ratings and Characteristics

Table 4 Source-Drain Diode Characteristics

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions
I_S	Continuous Source Current (Body Diode)	—	—	3.5	A	
I_{SM}	Pulsed Source Current (Body Diode) [1]	—	—	14	A	
V_{SD}	Diode Forward Voltage	—	—	1.5	V	T_J = 25°C, I_S = 3.5A, V_{GS} = 0V [2]
t_{rr}	Reverse Recovery Time	—	—	180	ns	T_J = 25°C, I_F = 3.5A, V_{DD} ≤ 50V di/dt = 100A/µs
Q_{rr}	Reverse Recovery Charge	—	1.3	—	µC	
t_{on}	Forward Turn-On Time	Intrinsic turn-on time is negligible (turn-on is dominated by L_S+L_D)				

2.3 Thermal Characteristics

Table 5 Thermal Resistance

Symbol	Parameter	Min.	Typ.	Max.	Unit
$R_{\theta JC}$	Junction-to-Case	—	—	8.33	°C/W
$R_{\theta J\text{-}PCB}$	Junction-to-PC Board (Soldered to a copper clad PC board)	—	—	27	

[1] Repetitive Rating; Pulse width limited by maximum junction temperature.

[2] Pulse width ≤ 300 µs; Duty Cycle ≤ 2%

3 Electrical Characteristics Curves

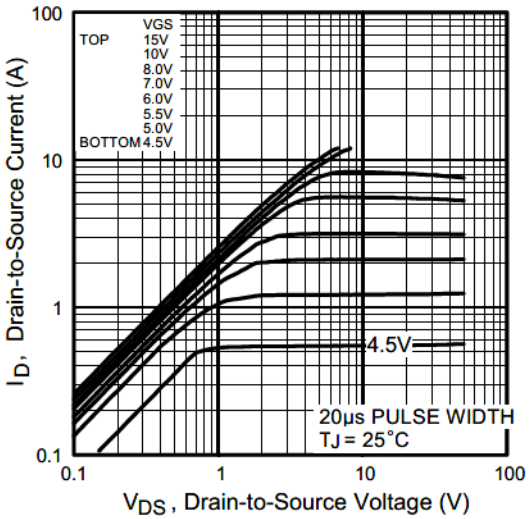


Figure 1 Typical Output Characteristics

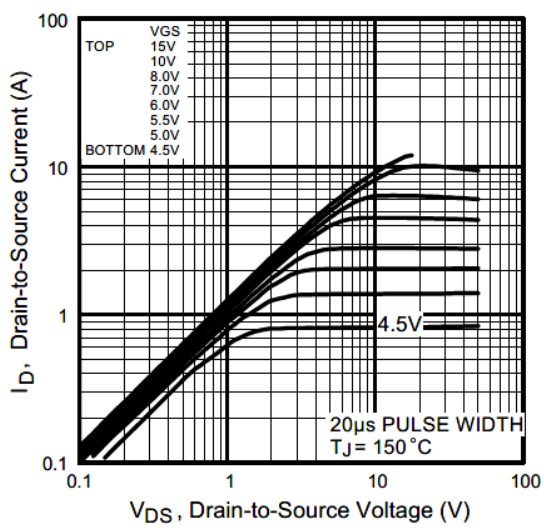


Figure 2 Typical Output Characteristics

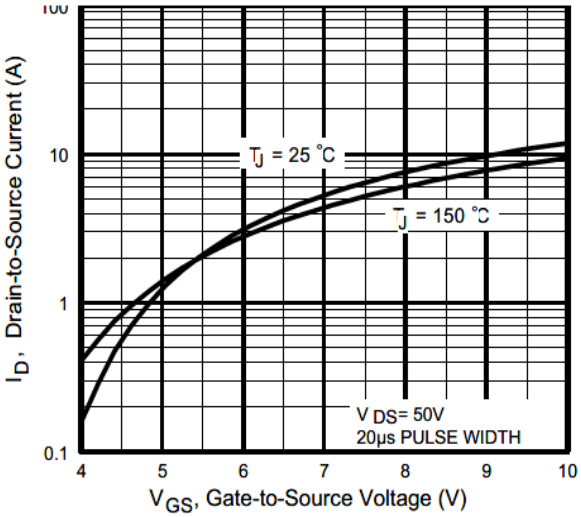


Figure 3 Typical Transfer Characteristics

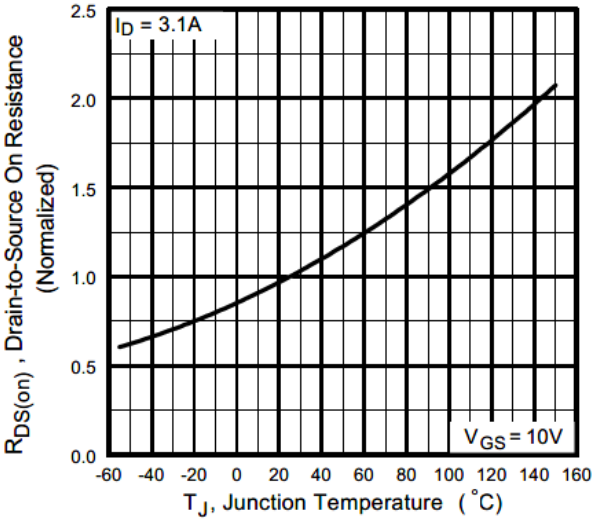


Figure 4 Normalized On-Resistance Vs. Temperature

Electrical Characteristics Curves

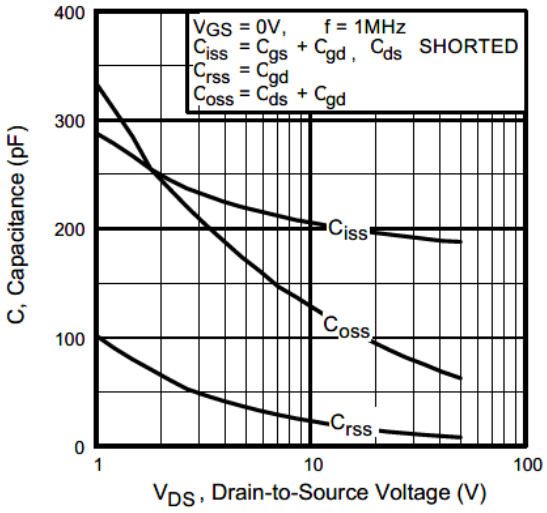


Figure 5 Typical Capacitance Vs. Drain-to-Source Voltage

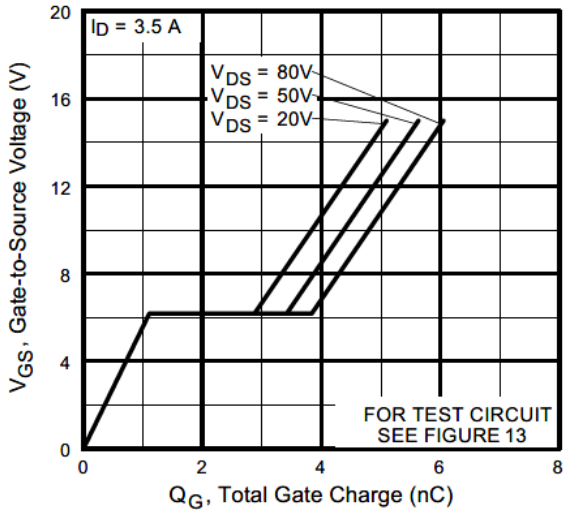


Figure 6 Typical Gate Charge Vs. Gate-to-Source Voltage

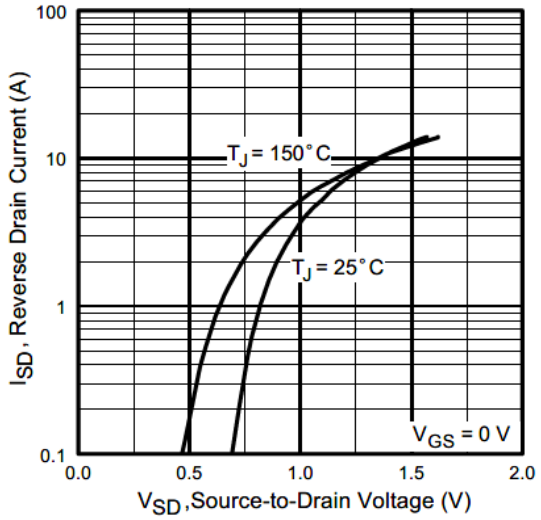


Figure 7 Typical Source-Drain Diode Forward Voltage

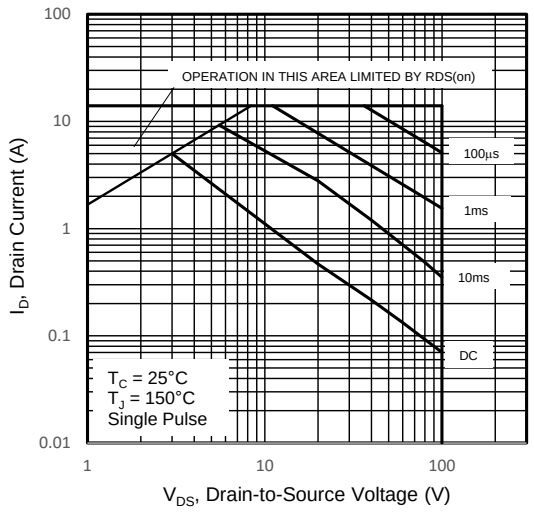


Figure 8 Maximum Safe Operating Area

Electrical Characteristics Curves

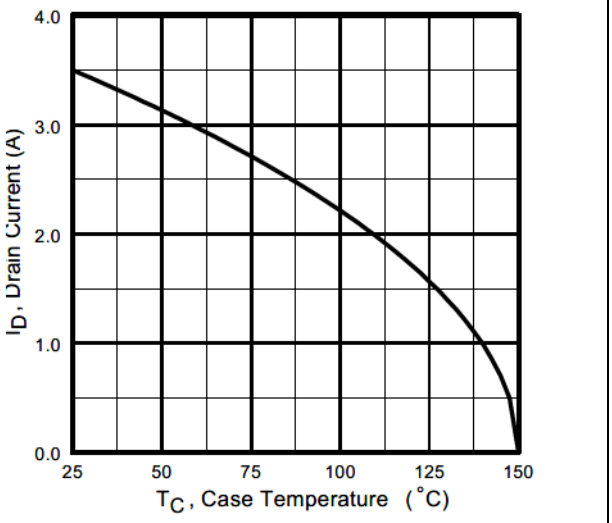


Figure 9 Maximum Drain Current Vs. Case Temperature

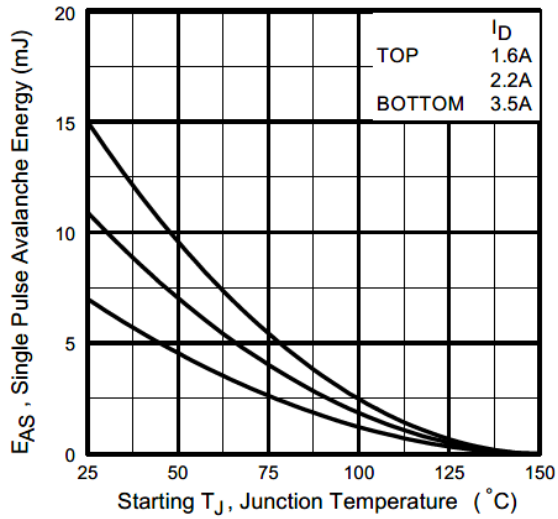


Figure 10 Maximum Avalanche Energy Vs. Junction Temperature

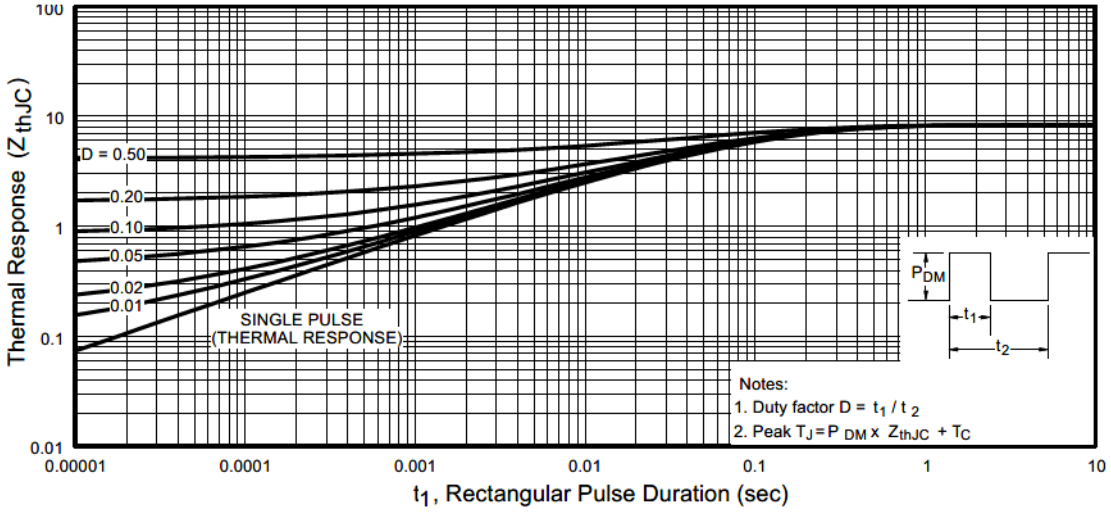


Figure 11 Maximum Effective Transient Thermal Impedance, Junction-to-Case

4 Test Circuits

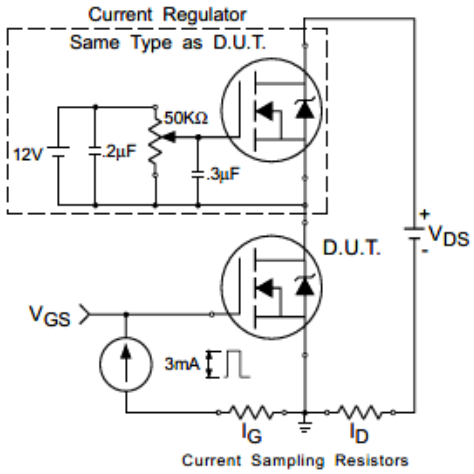


Figure 12 Gate Charge Test Circuit

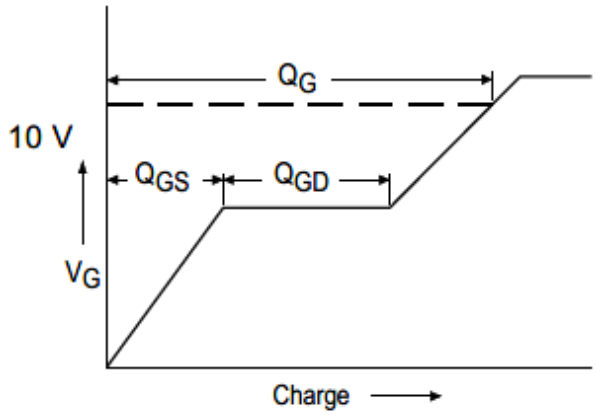


Figure 13 Gate Charge Waveform

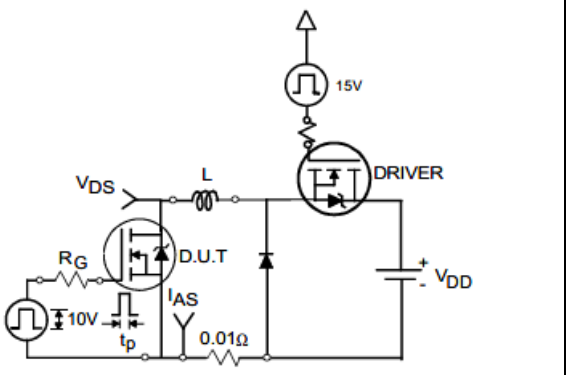


Figure 14 Unclamped Inductive Test Circuit

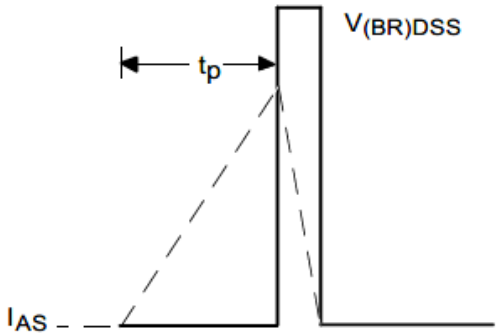


Figure 15 Unclamped Inductive Waveform

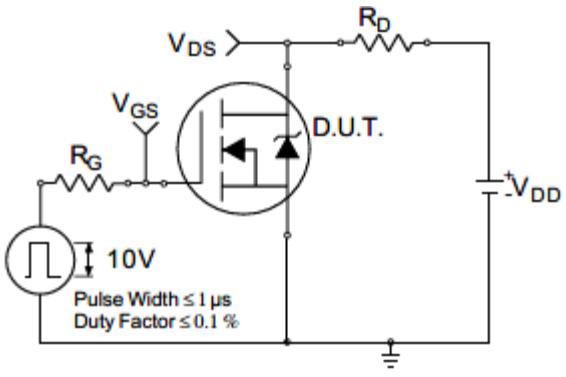


Figure 16 Switching Time Test Circuit

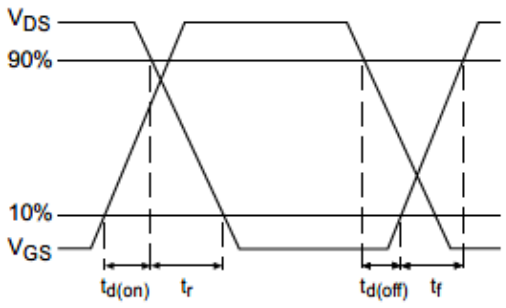
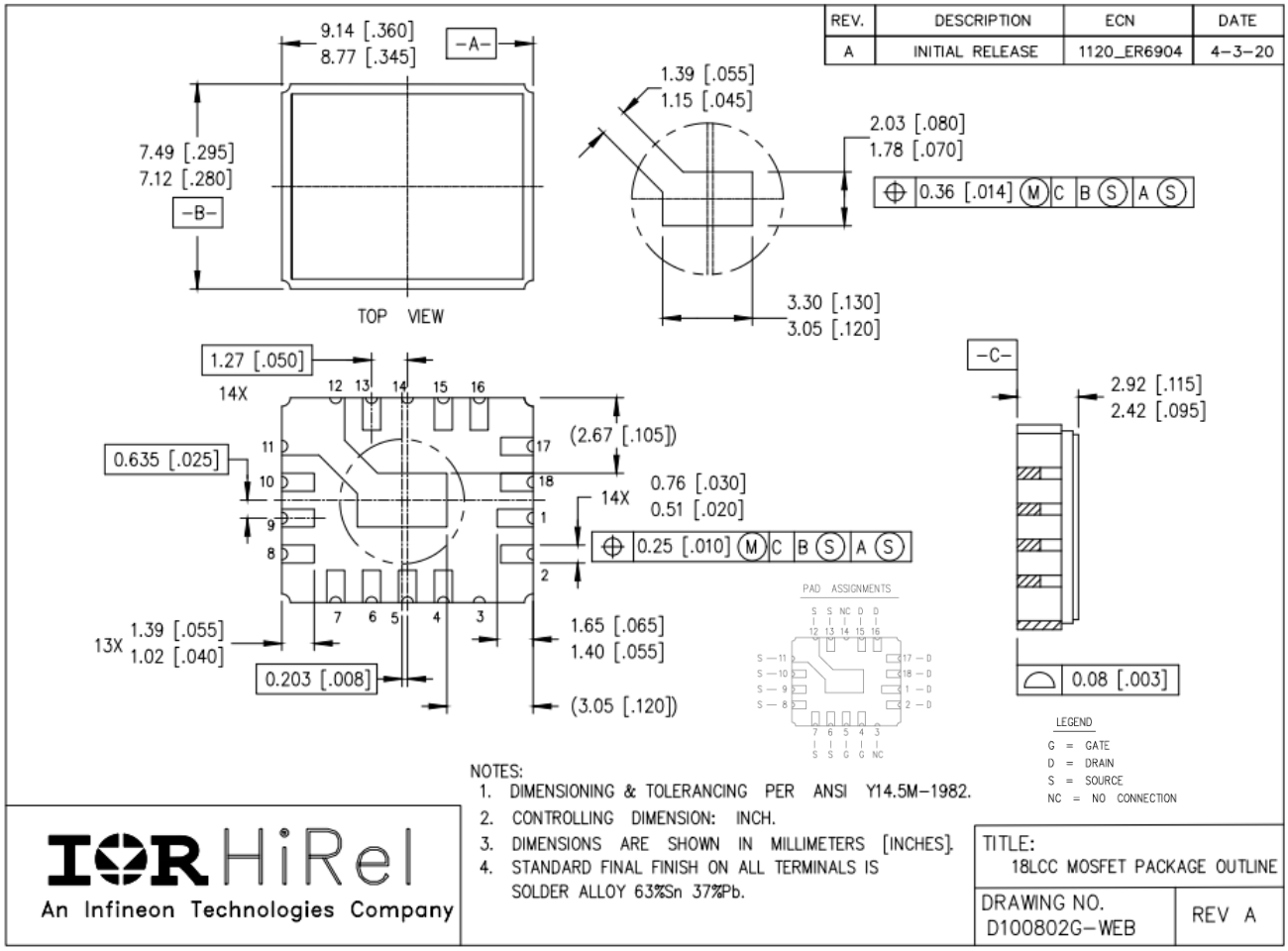


Figure 17 Switching Time Waveforms

5 Package Outline

Note: For the most updated package outline, please see the website: LCC-18



Revision history

Document version	Date of release	Description of changes
	01/25/2001	Datasheet (PD-91699B)
Rev C	12/08/2023	Updated based on ECN-1120_09755

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Edition 2023-12-08

Published by

International Rectifier HiRel Products, Inc.

An Infineon Technologies company

El Segundo, California 90245 USA

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Document reference

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